

FEATURES

- **LOW INTERMODULATION DISTORTION**
 IM3=-45 dBc at Po= 35.0dBm,
 Single Carrier Level
- **HIGH POWER**
 P1dB=45.5dBm at 7.7GHz to 8.5GHz
- **HIGH GAIN**
 G1dB=6.0dB at 7.7GHz to 8.5GHz
- **BROAD BAND INTERNALLY MATCHED FET**
- **HERMETICALLY SEALED PACKAGE**

RF PERFORMANCE SPECIFICATIONS (Ta= 25°C)

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Gain Compression Point	P1dB	VDS=10V f = 7.7 to 8.5GHz	dBm	45.0	45.5	—
Power Gain at 1dB Gain Compression Point	G1dB		dB	5.0	6.0	—
Drain Current	IDS1		A	—	8.0	9.0
Gain Flatness	ΔG		dB	—	—	±0.8
Power Added Efficiency	η _{add}		%	—	33	—
3rd Order Intermodulation Distortion	IM3	Two-Tone Test Po=35.0dBm	dBc	-42	-45	—
Drain Current	IDS2	(Single Carrier Level)	A	—	8.0	9.0
Channel Temperature Rise	ΔT _{ch}	VDS X IDS X Rth(c-c)	°C	—	—	100

Recommended Gate Resistance(Rg): 28 Ω (Max.)

ELECTRICAL CHARACTERISTICS (Ta= 25°C)

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	VDS= 3V IDS= 10.5A	mS	—	6500	—
Pinch-off Voltage	VGSoff	VDS= 3V IDS= 140mA	V	-1.0	-2.5	-4.0
Saturated Drain Current	IDSS	VDS= 3V VGS= 0V	A	—	20	26
Gate-Source Breakdown Voltage	VGSO	IGS= -420μA	V	-5	—	—
Thermal Resistance	Rth(c-c)	Channel to Case	°C/W	—	1.0	1.3

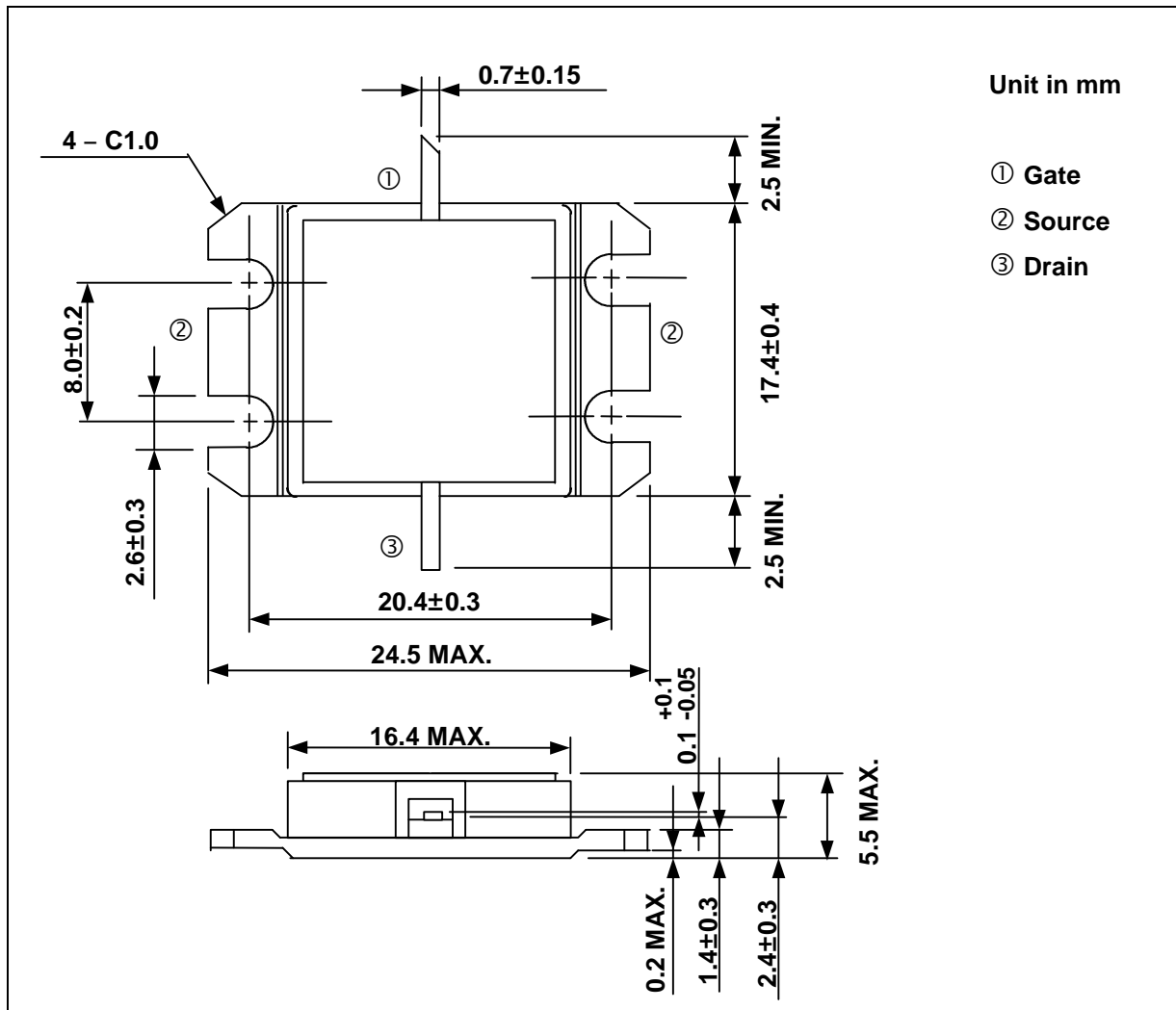
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The information contained herein is subject to change without prior notice. It is therefor advisable to contact TOSHIBA before proceeding with design of equipment incorporating this product.

ABSOLUTE MAXIMUM RATINGS (Ta= 25°C)

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	VDS	V	15
Gate-Source Voltage	VGS	V	-5
Drain Current	IDS	A	26
Total Power Dissipation (Tc= 25 °C)	PT	W	115
Channel Temperature	Tch	°C	175
Storage	Tstg	°C	-65 to +175

PACKAGE OUTLINE (2-16G1B)

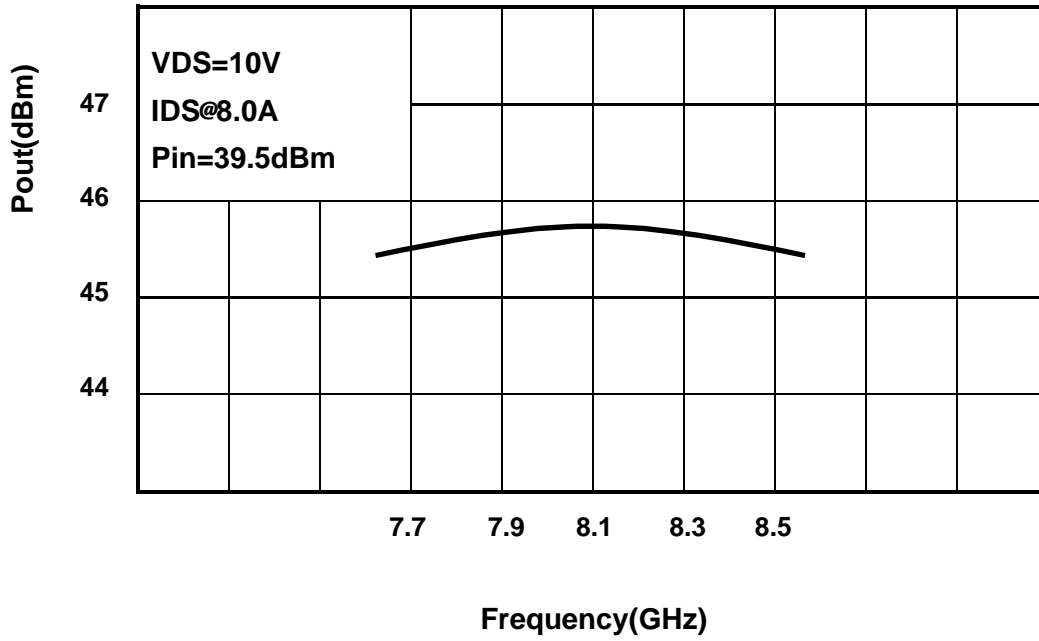


HANDLING PRECAUTIONS FOR PACKAGE MODEL

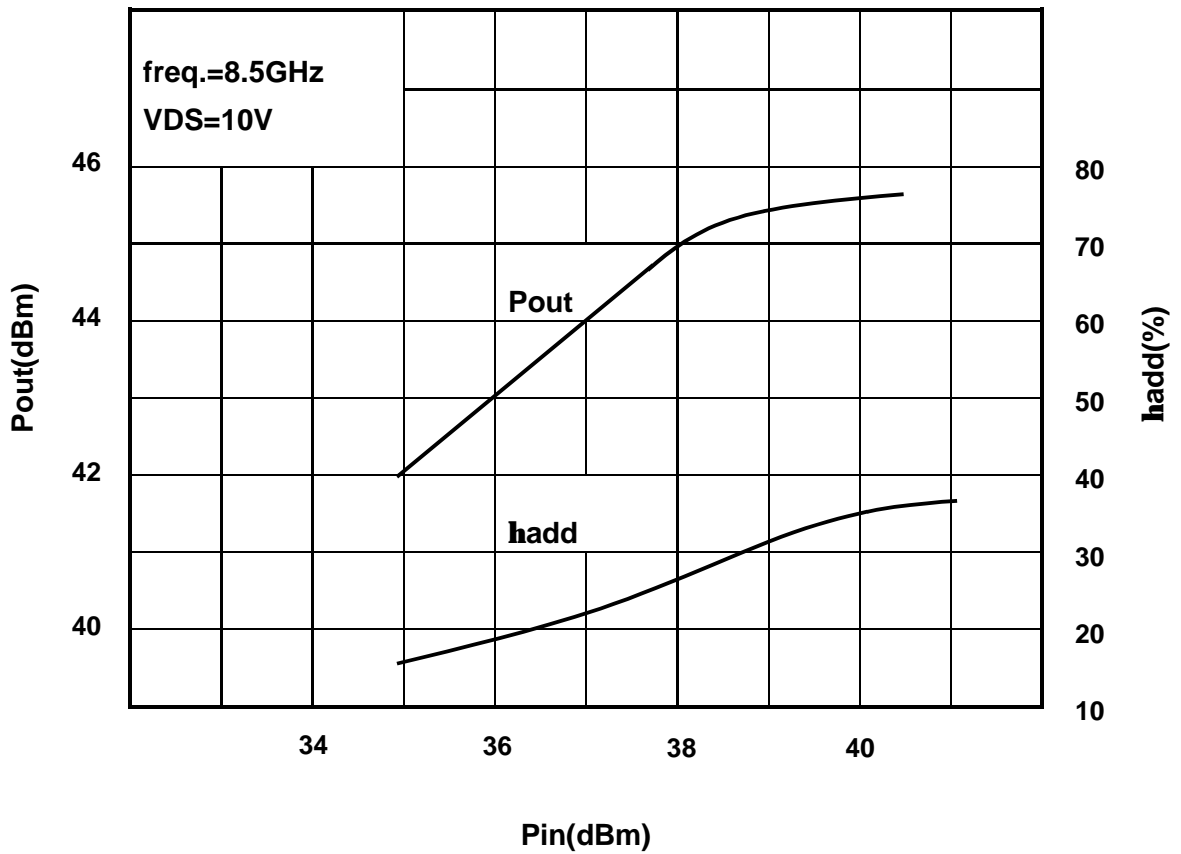
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF PERFORMANCE

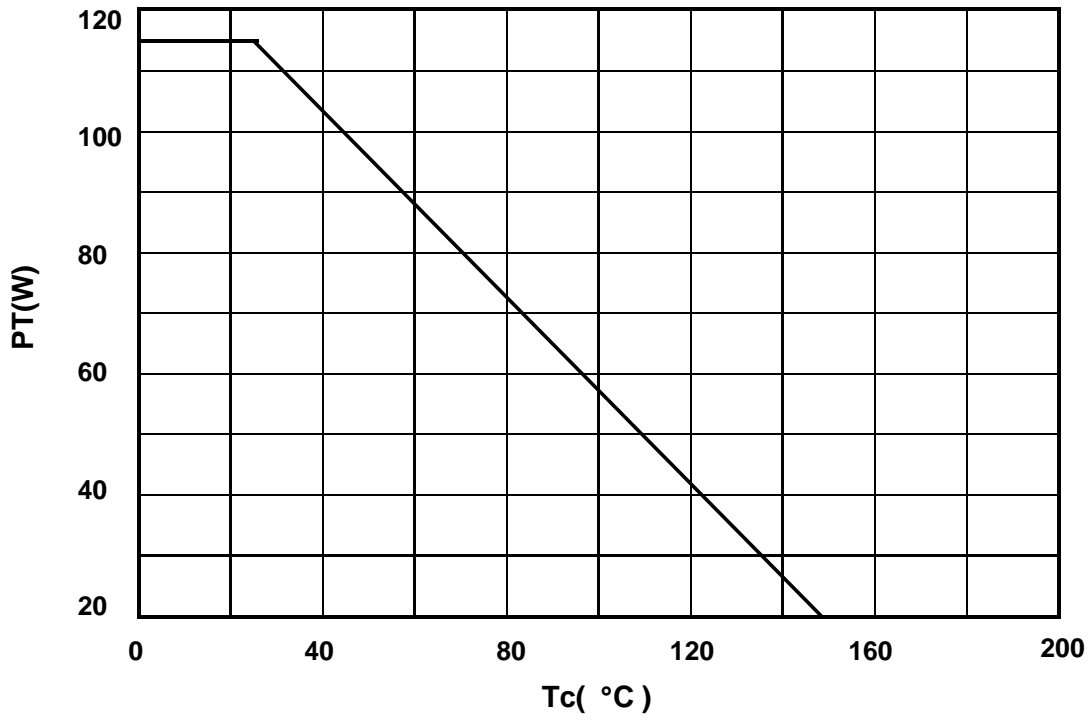
Output Power (Pout) vs. Frequency



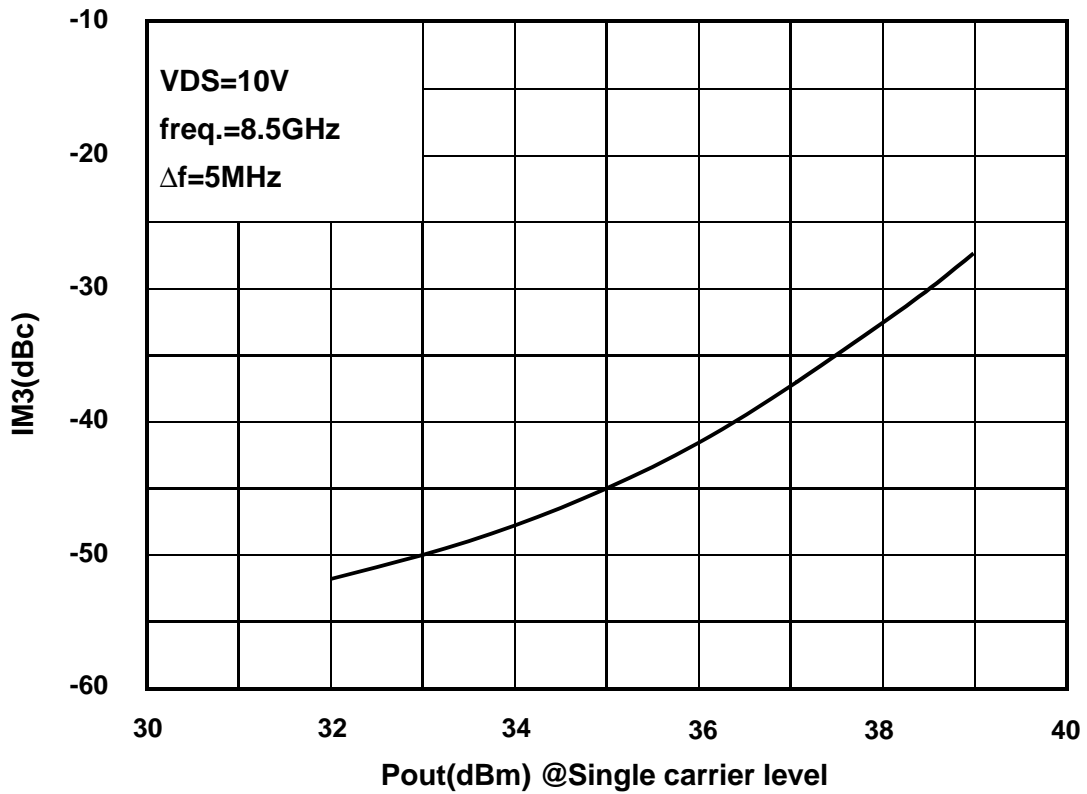
Output Power(Pout) vs. Input Power(Pin)



Power Dissipation(PT) vs. Case Temperature(Tc)

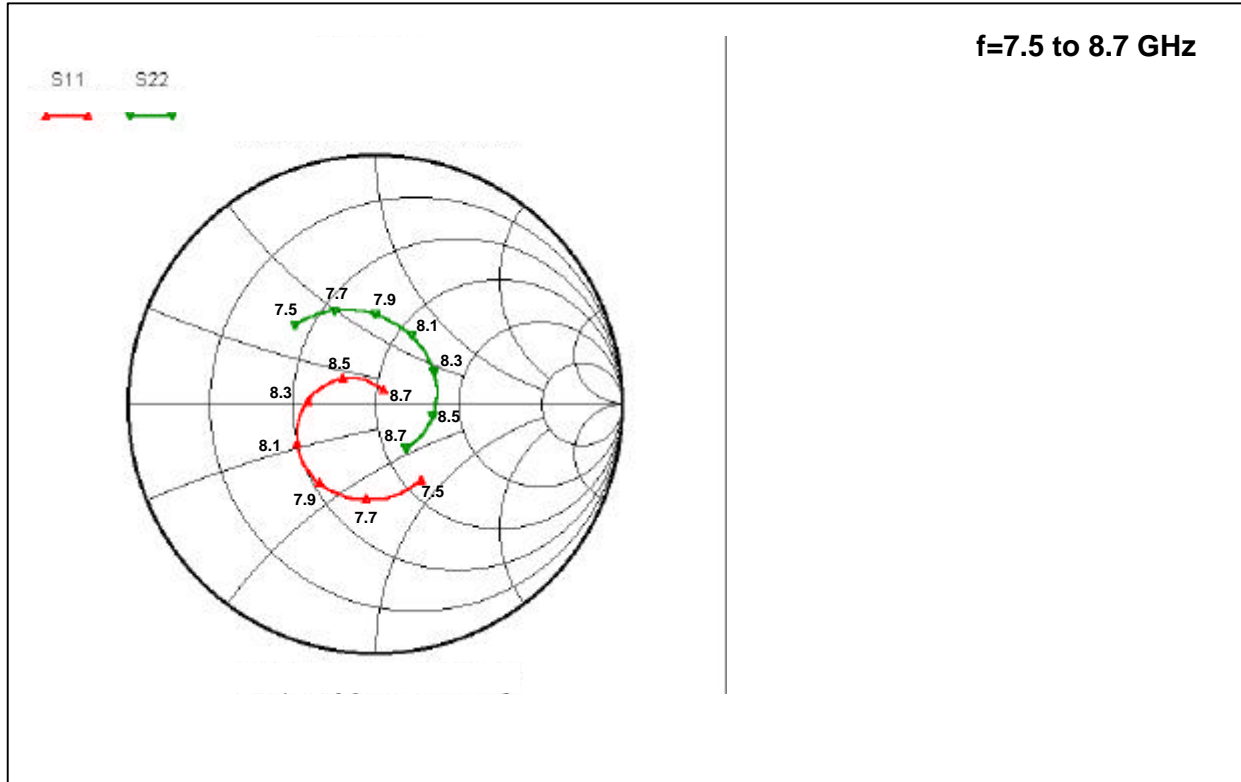


IM3 vs. Output Power Characteristics



**TIM7785-35SL S-PARAMETERS
(MAGN. and ANGLES)**

$V_{DS}=10V, I_{DS}=8.0A$



FREQUENCY (GHz)	S11		S12		S21		S22	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
7.50	-8.9814	-58.883	7.7466	-132.94	-26.718	-157.88	-6.814	135.77
7.70	-8.3276	-95.847	7.6201	178.84	-26.03	153.1	-7.7217	113.8
7.00	-8.2456	-125.79	7.5867	131.47	-25.415	105.53	-8.8479	90.07
8.10	-9.079	-153.45	7.6876	83.846	-24.785	58.534	-10.106	62.308
8.30	-11.201	177.35	7.8387	35.074	-24.184	10.528	-11.394	28.383
8.50	-15.55	141.44	7.9431	-15.135	-23.802	-38.853	-12.511	-11.132
8.70	-23.587	61.355	7.8793	-66.763	-23.776	-89.791	-13.44	-55.383